

ISSUE CLASSIFICATION	
Class	Subclass

FILED UNDER 35 U.S.C. §

PATENT NUMBER

U.S. UTILITY Patent Application

O.I.P.E.	PATENT DATE
AK SCANNED MS ② Q.A. AA	

APPLICATION NO. 09/719422	CONT/PRIOR D F	CLASS 156	SUBCLASS 242	ART UNIT 1734 1733	EXAMINER Musser
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APPLICANTS

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Yoshinori Watanabe

TITLE

Semiconductor chip resin-sealing method and adhesive tape for pasting lead frames or the like

PTO-2040
12/89

ISSUING CLASSIFICATION												
ORIGINAL				CROSS REFERENCE(S)								
CLASS		SUBCLASS		CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)							
INTERNATIONAL CLASSIFICATION												

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<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS Sheets Drwg. Figs. Drwg. Print Fig.		CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
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<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent No. _____	_____ (Primary Examiner) (Date)		ISSUE FEE	
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<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.	_____ (Legal Instruments Examiner) (Date)		ISSUE BATCH NUMBER	
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